

| Moisture sensitivity level: Level 1

FEATURES

Surface Mounting Design 5.0*5.0mm

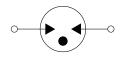
High Current Handling Capability 5,000A @ 8/20 µs

Low Capacitance and Insertion Loss

Quick Response and Long Service Life



5.0*5.0mm



APPLICATION INFORMATION Schematic Symbol

Communication equipment.

Repeaters, Modems

Telephone Interface, Line cards.

Data communication equipment.

AGENCY APPROVALS

lcon	Solderability	
RoHS	Compliance with 2011/65/EU	
HF	Compliance with IEC61249-2-21:2003	
Pb	Mean lead free	

PRODUCT CHARACTERISTICS

Lead Material	Body Material	Terminal Finish	
Copper or Fe-Ni alloy	Ceramics	100% Matte-Tin Plated	



ELECTRICAL PARAMETER

Parameter	Symbol	Limit	Unit
DC Blocking Voltage 1)	100V/s	800-1200	V
Impulse Spark-over Voltage	At 1kV/μs	for 99 % of measured values ≤ 1500	V
impuise spaik-over voltage	At 1kV/μs	Typical values of distribution ≤ 1400	V
Impulse Discharge Current 2)	8/20µs	5,000	А
Insulation Resistance	DC=100V	≥ 1	GΩ
Capacitance at 1MHz	V _{DC} =0.5V	≤ 1.5	
Operating And Storage Temperature		-40-125	°C

¹⁾ In ionized mode

ENVIRONMENTAL RELIABILITY CHARACTERISTICS

Testing items	Technical standards	
High Temperature Storage Test	Temperature: 85°C ; Time:2H	
Low Temperature Storage Test	Temperature: -40°C ; Time:2H	
Vibration	Frequency: 10-500Hz ; Amplitude: 0.15mm ; Time:45min	
Resistance of soldering heat	Temperature: 260±5°C; Time of dip soldering: 10s, 1time	

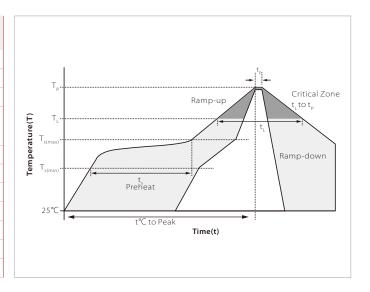
NOTE: Up-screen program can be specified by customer's request via contacting Semiware service

²⁾ Terms and waveforms in accordance with ITU-T Rec. K. 12; IEC 61643-21

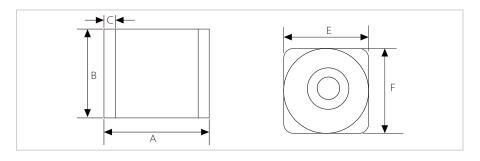


REFLOW PROFILE

Reflow Condition		Lead-free assembly	
	Temperature Min	150°C	
Pre Heat	Temperature Max	200°C	
	Time(min to max)	60 – 180 secs	
Average ra	amp up rate (Liquidus) $Temp(T_L)$ to peak	3°C/second max	
	T_s (max)to T_L - Ramp-up Rate		
Reflow	Temperature (T_L) (Liquidus)	217℃	
Kellow	Time(min to max)(t_s)	60 – 150 seconds	
Peak Tem	perature (T,)	260°C	
Time within 5°C of actual peak Temperature (tp)		10-30 seconds	
Ramp-down Rate		6°C/second max	
Time 25°C to peak Temperature (T,)		8 minutes max.	
Do not exceed		260°C	



PRODUCT DIMENSIONS AND RECOMMENDED SOLDERING PAD



Ref.	Outline Dimensions	
Kei.	Millimeters	
А	5.0±0.3	
В	5.0±0.3	
С	0.5±0.1	
E	5.0±0.3	
F	5.0±0.3	

ORDERING INFORMATION

Part Number	Size	Marking	QTY/Reel	Reel Size
SG2D05B1000	5.0*5.0mm	愛 SG1000 <u>05</u>	1000PCS	13″



Headquarters

No.3387 Shendu Road Pujiang I&E Park Minhang Shanghai China 201000

Hotline

400-021-5756

Web

Https://www.semiware.com

Sales Center

Tel: 86-21-3463-7458 Email: sales18@semiware.com

Customer Service

Tel: 86-21-5484-1001 Email: sales17@semiware.com

Technical Support

Tel: 86-21-3463-7654 Email: fae01@semiware.com

Complaint & Suggestions

Tel: 86-21-3463-7172 Ext: 8868 Email: cs03@semiware.com

By QR Code





Website

\A/achat

To find your local partner within Semiware's global network: www.semiware.com

2022 Semiware Semiconductor Inc.

The content of this document has been carefully checked and understood. However, neither Semiware nor its subsidiaries assume any liability whatsoever for any errors or inaccuracies of this document and theconsequences thereof. Published specifications are subject to change without notice. Product suitability for any area of application must ultimately be determined by the customer. In all cases, products must never be operated outside their published specifications. Semiware does not guarantee the availability of all published products. This disclaimer shall be governed by substantive Chinese law and resulting disputes shall be settled by the courts at the place of business of Semiware. Latest publications and a complete disclaimer can be downloaded from the Semiware website. All trademarks recognized.